



Soft Touch™

Model 616A-005

Digital Thermosonic Peg Bonder

For 0.5 - 2.0mil (12.5 - 50 micron) dia. insulated wire, 0.5 - 3.0 mil (12.5 - 75 micron) dia. bare wire and up to 1 x 20 (25 - 500 micron) gold or aluminum wire, ribbon or gold plated copper leads



Standard Features:

- HYBOND *Soft Touch™* bond force system.
- Servo-motor vertical (Z axis) control.
- 0.75in. vertical bonding window.
- Variable height bonding within 0.75in.
- Search height adjustable in 0.001in. increments.
- Hi/Lo U/S power selector (PLL generator).
- Digital parameter adjustment in actual units (Watts, milliseconds and grams).
- Storage for up to ten bond schedules in non-volatile memory.
- Built-in temperature controller.
- Bond counter records number of bonds performed and can be reset.
- Dual footswitch control for bond head vertical (up and down) movement.
- Bond head vertical movement can be controlled in fast or slow speeds on manual mode.
- Bond level sensor system stops Z axis movement upon contact with bond surface and activates bond cycle.
- Deep access when using 0.750in. tool.

HYBOND's Model 616A-005 thermosonic single channel Peg Bonder is designed for ultrasonic and thermosonic bonding of interconnects in applications that do not require the bonder to feed wire. Applications include "tacking" tuning ribbons, insulated wire bonding, flex on flex bonding, pin tab bonding, mesh bonding and ball coining. When fitted with Hybond's OP-47, the 616A-005 becomes a Beam Lead Diode (BLD) Bonder allowing the operator to pick up, place and bond the BLD without pre-positioning.

Partial List of Available Options:

OP-06S6: Leica S6 Stereo Zoom Microscope.	WST-15A: Heated Work Stage, 2.125in. Top
OP-06A: Nikon SMZ660 Microscope.	WST-15A/WP: Heated Work Stage, 2.125in. Top. with 2x2in.
OP-08A: Dual Fiber Optic Illuminator.	Waffle Pack/Tray holder for Beam Lead Diodes (Use with OP-47).
OP-08R/LED: LED Ring Illuminator.	PT-X.X: Peg Tool (sizes and styles vary, match to application).
OP-12: 240VAC 50/60Hz Input Wiring.	PT-BLDB: Peg Tool for Beam Lead Diode Bonding.

Specifications for Model 616A-005:

Ultrasonics (U/S):	PLL self tuning 62.5KHz (nominal) system (+/- 2.5KHz).
U/S Power:	0-2 Watts on low setting and 0-4Watts on high setting.
Bond Time:	0-900mS.
Bond Force:	12 to 300g
Temperature Control Range:	15 to 250 degrees Centigrade.
Bond Head Movement:	True vertical motorized movement with fast and slow speeds in manual mode or search height pause in auto mode.
Bond Actuation:	Bond height sensor activates bond cycle upon contact with bond surface/overtravel.
Microscope:	Zoom stereo microscope with maximum magnification of 60X or better.
Illumination System:	Dual fiber optic "goose neck" system or white LED ring illuminator system available.
Work Stage:	Unheated or heated (using model 400A) standard and custom stages available.
X-Y Work Platform Motion:	Manual, 4:1 ratio between manipulator and X-Y table.
Input Power Requirements:	120 VAC 50-60Hz @10A (max.) Standard, 240VAC optional (See OP-12).
Minimum Bench Space Required:	20.0 x 20.0in. (50,8 x 50,8cm).
Unit Weight:	Approximately 45Lbs. (20Kg).
Shipping Weight:	Approximately 135Lbs. (61.2Kg). Shipping weight varies depending on accessories.



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